

IN THE SPECIFICATION

Please amend the Title on page 1 as follows:

MOUNTING METHOD OF MAGNETIC HEAD COMPONENT, MAGNETIC HEAD
DEVICE AND MANUFACTURING METHOD OF MAGNETIC HEAD DEVICE
UTILIZING SOLDER BALLS WITH NONMELTING CORES

Please replace the paragraph beginning at page 9, line 9, with the following rewritten paragraph:

The molten-solder connections can be performed with keeping the shape of each core of the solder ball as it is because the core will not melt even when the temperature rises to a solder-melting temperature or more. Therefore, the solder connections can be very easily controlled. Also, since the shape of the solder connections is stable, variations in roll angle and pitch angle of the magnetic head slider, which variations may occur during the solder connection, can be reduced and stabilized. As a result, flying performance of the magnetic head slider and therefore its output characteristics can be kept stable. Furthermore, because of the stable shape of the solder connections, ~~rework~~ reworking of the magnetic head device after the solder reflow connections becomes easy to accomplish.

Please replace the heading at page 13, line 18, as follows:

DETAILED DESCRIPTION OF THE ~~INVENTION~~ PREFERRED
EMBODIMENTS

Please replace the paragraph beginning at page 13, line 19, with the following rewritten paragraph:

FIG. 1 illustrates an HGA as seen from a slider-mounting side as a preferred embodiment of a magnetic head device according to the present invention, FIG. 2 illustrates

the HGA shown in FIG. 1 as seen from the opposite side of the slider-mounting side, and FIG. 3 illustrates an enlarged top end section of the HGA shown in FIGS. 1 and 2.

Please replace the paragraph beginning at page 16, line 16, with the following rewritten paragraph:

The terminal pads 13b of the magnetic head slider 13 and the connection pads 14b of the lead conductor member 14 are connected with each other by reflowed solders 17, respectively. Each reflowed solder 17 is formed by laser reflowing of a solder ball 15 supplied at [[a]] an exposed corner or juncture between the second surface of the flexure 12 and the element formed surface 13e of the slider body 13a as shown in Figure 3, for example. By means of this solder connection of the terminal pads 13b of the magnetic head slider 13 with the connection pads 14b of the lead conductor member 14, the magnetic write head element and the magnetic read head element of the magnetic head slider 13 are electrically connected with the trace conductors 14a of the lead conductor member 14.

Please replace the paragraph beginning at page 17, line 10, with the following rewritten paragraph:

In the example of FIG. 4a, the whole of a sphere core 40 is made of metal material containing at least copper, such as copper or copper alloy, and a solder layer 41 are coated to cover the entire surface of the core 40. In this example, a diameter of the core 40 is about 80-100 μm , a thickness of the solder layer 41 is about 10 μm and a total diameter of the solder ball is about 100-120 μm . It is necessary that a volume of the core 40 is 30-70% of the total volume of the solder ball. Also, it is desired that the diameter of the core 40 is smaller than a longitudinal direction length of the terminal pad 13b of the magnetic head slider 13 and than a longitudinal direction length of the connection pad 14b of the lead conductor member 14.

As will be noted from FIG. 3, when such solder ball with a core is used, actual soldering portion will be concentrated on the upper region of each terminal pad 13b of the magnetic head slider 13. Thus, if the diameter of the core 40 is large, an area used for the soldering connection decreases. Therefore, in order to secure [[an]] enough solder connection area, it is preferred that the diameter or height of the core 40 is smaller than the longitudinal direction length or height of the terminal pad 13b. Due to the similar reasons, it is preferred that the diameter of the core 40 is smaller than the longitudinal direction length of the connection pad 14b of the lead conductor member 14. Any material other than the metal material can be used as the core 40 on conditions that it will not melt even when the temperature rises to a solder-melting temperature or more. For example, the core 40 may be made of a resin material. Preferably, the material of the core 40 is that with an excellent solder wettability and with a high thermal conductivity. As for solder balls with resin material cores, plastic core solder balls called Micropearl SOL provided from Sekisui Chemical Co., Ltd. may be used.